

Lead free solder Product information

Lead Free Solder Wire for Robotic Soldering ASW01-C114

Sn-Ag-Cu series
Lead free flux cored solder wire

- MIL-RMA, JIS-A, IPC-ROL1 type lead free type flux cored wire solder.
- Good wettability and low flux spattering at soldering.
- Supports both laser and iron soldering.
- Light color flux residue.

Characteristics

Item	Characteristics	Test Method
Alloy composition (%)	Sn:balance, Ag:3.0, Cu:0.5	Allowable impurity level is based on JIS Z 3282.
Solidus temperature (°C)	217	DSC (Differential Scanning Calorimetry)
Liquidus temperature (°C)	220	
Flux content (%)	4.0	JIS Z 3197 8.1.2
Halide content (%)	0.11	JIS Z 3197 8.1.4.2.1
Copper mirror test	No corrosion	JIS Z 3197 8.4.2
Cooper plate corrosion test	No corrosion	JIS Z 3197 8.4.1
Insulation resistance test (Ω)	More than 5.0×10^8	JIS Z 3197 8.5.3 JIS Type, 85°C-85%RH, 168h, measured with DC100v inside of chamber
Migration test	No migration	JIS Z 3197 8.5.3 JIS Type, 85°C-85%RH, 1000h, applied with DC48v, visual check
Aqueous solution resistance test (Ω m)	More than 1000	JIS Z 3197 8.1.1
Dryness test	Passed	JIS Z 3197 8.5.1
Spreading factor test (%)	78.6	JIS Z 3197 8.3.1.1
Remarks	JIS Z 3282:2006 Solders-Chemical compositions and forms JIS Z 3197:1999 Testing method for soldering fluxes	

The above data is representative value.